

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
LEI ZOU	02/20/2020
GINO ROCCA	06/02/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TDK CORPORATION
<b>Street Address:</b>	2-5-1, NIHONBASHI, CHUO-KU
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	103-6128
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16475061
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(972)732-9218
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	972-732-1001
<b>Email:</b>	docketing@slatermatsil.com
<b>Correspondent Name:</b>	SLATER MATSIL, LLP
<b>Address Line 1:</b>	17950 PRESTON RD., SUITE 1000
<b>Address Line 4:</b>	DALLAS, TEXAS 75252
<b>ATTORNEY DOCKET NUMBER:</b>	EPC-501-EH
<b>NAME OF SUBMITTER:</b>	KASEY CORCORAN
<b>SIGNATURE:</b>	/Kasey Corcoran/
<b>DATE SIGNED:</b>	06/17/2020
<b>Total Attachments: 4</b>	
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source=EPC-501-EH_Assignment#page4.tif	

## ASSIGNMENT

For good and valuable consideration,

- I, Lei Zou, residing at Smedsrudveien 22D, 1405 LANGHUS, NORWAY, a citizen of CHINA;
- I, Gino Rocca, residing at Havneholmen 62, 1MF, 1561 COPENHAGEN, DENMARK, a citizen of ITALY;

hereby sell, assign, and transfer or confirm that I have sold, assigned and transferred to TDK Corporation, a corporation organized and existing under the laws of Japan, having its principal place of business at Tokyo, Japan.

hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the invention report with the title

"Sub-1uA low-noise high-PSRR bandgap reference and readout circuit with a bandgap",  
dated May 2, 2016, (EHF-reference: E2016,0479)

including all patent applications therefor that may have been filed or may be filed hereafter for said improvements in the United States, or under International Conventions, Treaties, or Agreements (collectively the "INVENTIONS"), including but not limited to US Patent Application

Filing No.: 16/475,061

Filing Date: June 28, 2019

Title: Bandgap reference circuit and method for providing a reference voltage

and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number, filing date and title;

and in and to all divisional, continuing substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said INVENTIONS; and in and to all original and reissued patents

which have been or shall be filed in the United States and all foreign countries on said INVENTIONS;

Agree that Assignee may apply for and receive Letters Patent for said INVENTIONS in its own name, and that, when requested, without charge to but at the expense of said Assignee, their successors, assigns, and legal representatives to carry out in good faith the intent and purpose of this agreement, the undersigned will execute all divisional, continuing substitute, renewal, reissue, and all other patent applications on any and all said INVENTIONS; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said INVENTION and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said INVENTIONS and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date: February 20, 2020

  
Lei Zou

Date: \_\_\_\_\_

\_\_\_\_\_  
Gino Rocca

## ASSIGNMENT

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- I, Lei Zou, residing at Smedsrudveien 22D, 1405 LANGHUS, NORWAY, a citizen of CHINA;
- I, Gino Rocca, residing at Havneholmen 62, 1MF, 1561 COPENHAGEN, DENMARK, a citizen of ITALY;

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Filing No.: 16/475,061

Filing Date: June 28, 2019

Title: Bandgap reference circuit and method for providing a reference voltage

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which have been or shall be filed in the United States and all foreign countries on said INVENTIONS;


Agree that Assignee may apply for and receive Letters Patent for said INVENTIONS in its own name, and that, when requested, without charge to but at the expense of said Assignee, their successors, assigns, and legal representatives to carry out in good faith the intent and purpose of this agreement, the undersigned will execute all divisional, continuing substitute, renewal, reissue, and all other patent applications on any and all said INVENTIONS; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said INVENTION and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said INVENTIONS and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date: \_\_\_\_\_

\_\_\_\_\_  
Lei Zou

Date: 2/6/2020

  
\_\_\_\_\_  
Gino Rocca